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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Ajit V. SATHE

Serial No.: 09/893,466

Filed: 29 June 2001

For: Arrangements To Provide Mechanical Stiffening Elements To A Thin-Core Or Coreless Substrate

Art Unit: 2827

Examiner: Ishwarbhai B. Patel

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TECHNOLOGY CENTER 2827#5/Election/a
DEVANS
3-21-02**AMENDMENT AND ELECTION**Assistant Commissioner for Patents
Washington, D.C. 20231

12 March 2002

Sir:

In response to the Office Action having a USPTO mailing date of 12 February 2002, the following is respectfully submitted in connection with the above-identified application.

IN THE CLAIMS:

Note that the full text of all claims (including those not being amended within this paper) may also be included to provide the convenience of a complete set of claims for easy review:

1. A stiffener to provide stiffening support to one of a thin-core and coreless

substrate of an integrated circuit printed circuit board (IC-PCB) carrier package.

03/15/2002 CV0111 00000118 09893466

01 FC:102
02 FC:103168.00 OP
216.00 OP